

**Amendments to the Specification (other than claims):**

Please replace paragraph [0083] with the following amended paragraph:

[0083] The wafer holder into which the foregoing electrodes had been attached was mounted as represented in Fig. 1 on a pedestal 15 made of SUS steel, via cylindrical support pieces 7 also made of SUS steel. This assembly was installed in the processing-chamber 10 interior of a semiconductor manufacturing device, and with bellows 16 made of nickel a hermetic seal was formed between the pedestal and the chamber. In this case, in 3 equidistantly spaced places in the wafer holder holes for penetration by the lift pins 5 were provided, wherein the wafer holder was set into place so that the lift pins 5 having been fixed to the chamber 10 would penetrate through the holes. The heights of the tip-end faces of the three lift pins were adjusted so that the height variance would be within 0.5 mm.